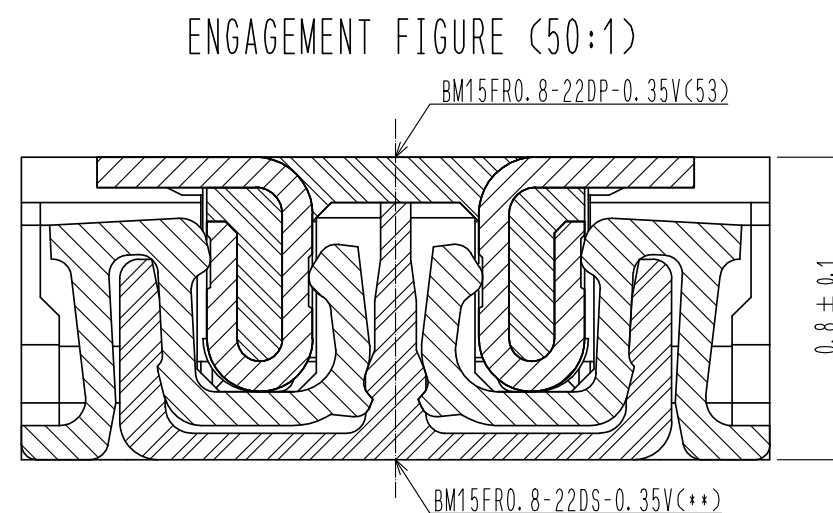
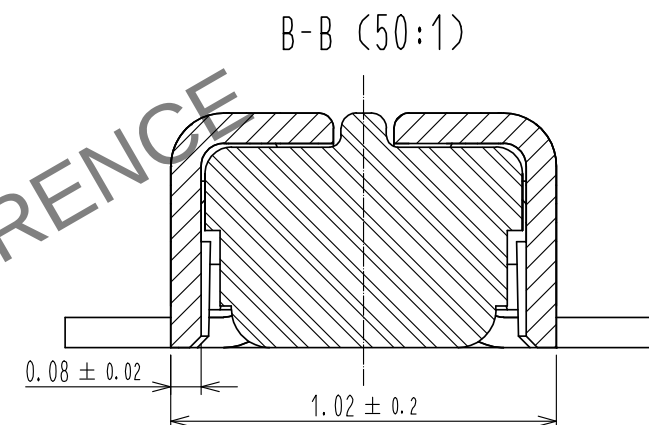
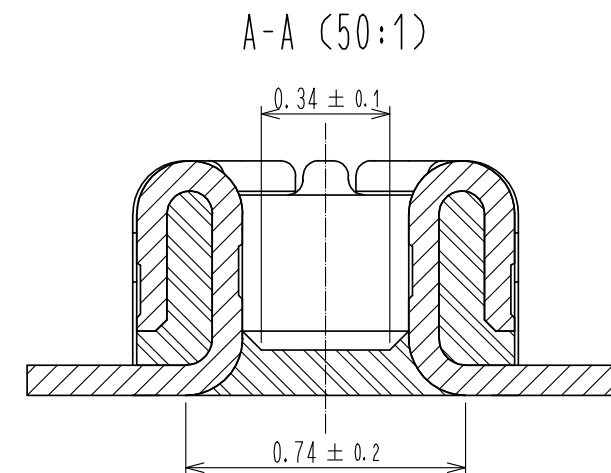
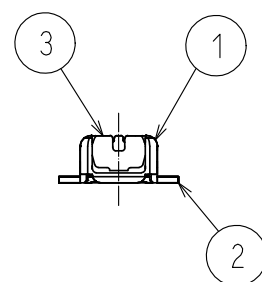
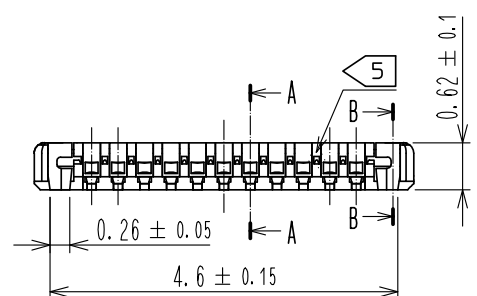
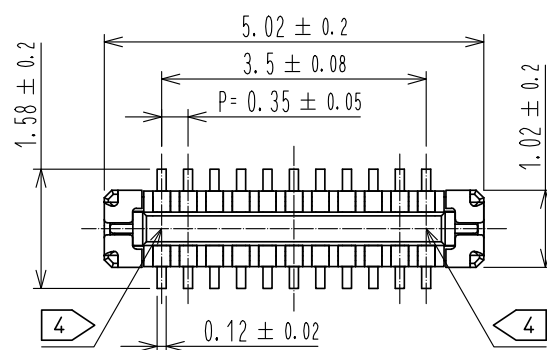


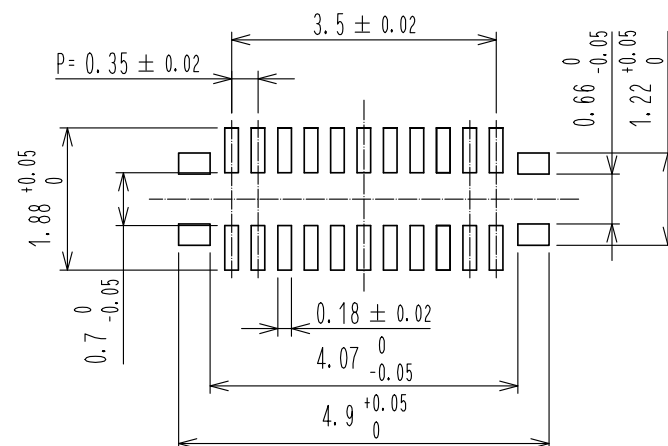


- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX  
2. CONTACT PLATING SPECIFICATIONS  
CONTACT AREA : GOLD 0.05μm MIN  
SMT LEAD : GOLD 0.05μm MIN  
UNDERPLATING : NICKEL 1μm MIN  
( SURFACE : SEALING )  
3. REINFORCED METAL FITTINGS LOCK  
SMT LEAD : GOLD 0.05μm MIN  
UNDERPLATING : NICKEL 1μm MIN  
( SURFACE : SEALING )  
4. CAV No. AND HRS MARK MYE BE INDICATED IN APPROX POSITION SHOWN.  
5. A PART OF THE WALL COULD BE NOTCHED.

|                           |                 |                               |           |                          |                              |
|---------------------------|-----------------|-------------------------------|-----------|--------------------------|------------------------------|
| 4                         | PS              | CLEAR (ENBOSSED CARRIER TAPE) |           |                          |                              |
| 3                         | PHOSPHOR BRONZE | 3                             | 7         | PS                       | CLEAR (REINFORCEMENT COLLAR) |
| 2                         | PHOSPHOR BRONZE | 2                             | 6         | PS                       | BLACK (PLASTIC REEL)         |
| 1                         | LCP             | UL94 V-0, BLACK               | 5         | POLYESTER                | CLEAR (COVER TAPE)           |
| NO.                       | MATERIAL        | FINISH . REMARKS              | NO.       | MATERIAL                 | FINISH . REMARKS             |
| UNITS<br>mm               |                 | SCALE<br>10 : 1               | COUNT<br> | DESCRIPTION OF REVISIONS | DESIGNED                     |
| HIROSE ELECTRIC CO., LTD. |                 | APPROVED : MO. ISHIDA         | 16.01.08  | DRAWING NO.              | EDC-355558-53-01             |
|                           |                 | CHECKED : TS. MIYAZAKI        | 16.01.08  | PART NO.                 | BM15FR0.8-22DP-0.35V(53)     |
|                           |                 | DESIGNED : SH. HOSODA         | 16.01.07  | CODE NO.                 | CL673-1224-2-53              |
|                           |                 | DRAWN : KR. AJITO             | 16.01.07  |                          |                              |
|                           |                 |                               |           |                          | 1/3                          |

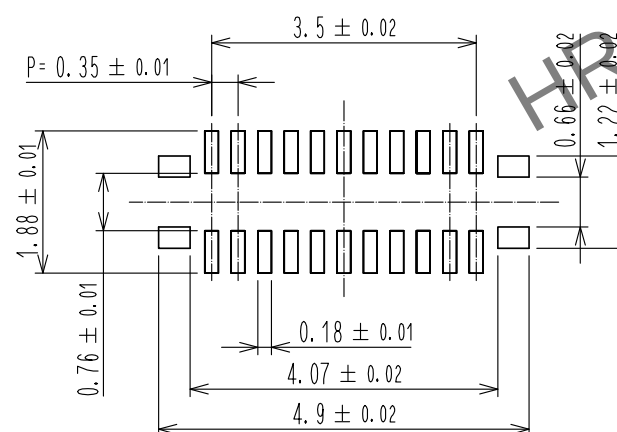
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In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

## ◆ RECOMMENDED PCB LAYOUT

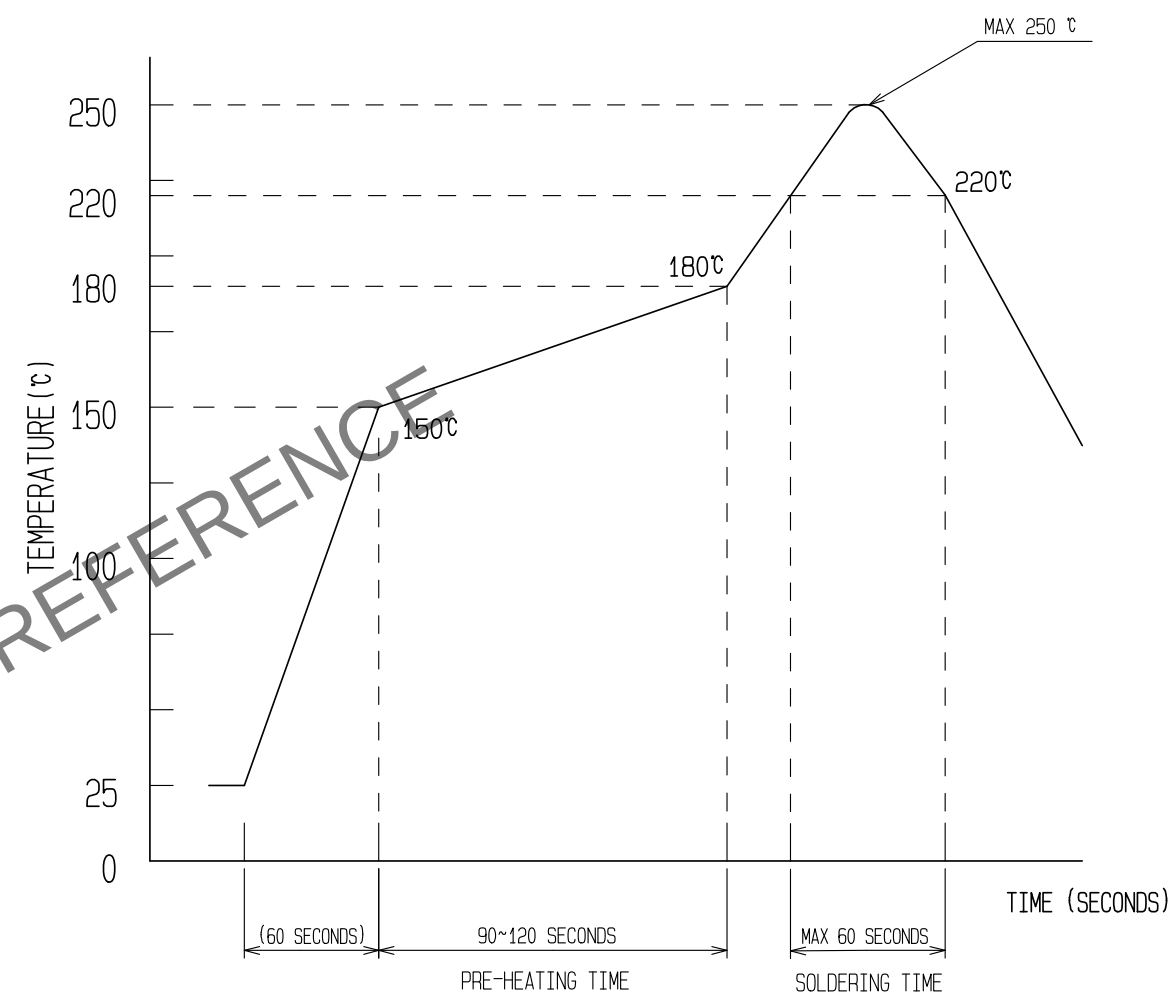


## ◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS :  $100 \mu\text{m}$



## 6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD: IR REFLOW  
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- 1) REFLOW TIME  
DURATION ABOVE 220°C, 60 SEC. MAX.  
(PEAK TEMPERATURE: 250°C MAX)
  - 2) PRE-HEAT TIME  
PRE-HEAT TEMPERATURE(MIN): 150°C  
PRE-HEAT TEMPERATURE(MAX): 180°C  
PRE-HEAT TIME: 90-120 sec.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.  
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND  
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,  
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED  
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

**HRS**

|             |                          |
|-------------|--------------------------|
| DRAWING NO. | EDC-355558-53-01         |
| PART NO.    | BM15FR0.8-22DP-0.35V(53) |
| CODE NO.    | CL673-1224-2-53          |

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